

IN THE CLAIMS

1    ~~13 (canceled).    A method of manufacturing an electronic component to be mounted on a~~  
2    ~~circuit board, said electronic component comprising:~~

3            ~~a first substrate having an electronic circuit device and an electrode pad on one main~~  
4    ~~surface of said first substrate in electrical connection with said electronic circuit device;~~

5            ~~a sealing wall whose one face is closely adhered to said one main surface of said first~~  
6    ~~substrate, said sealing wall being configured, to enclose said electronic circuit device with said~~  
7    ~~electrode pad arranged outside of said sealing wall;~~

8            ~~a second substrate closely adhered to the other face of said sealing wall;~~

9            ~~an opening formed in said second substrate at a site confronting said electrode pad; and~~

10           ~~an electrically conductive member extending through the interior of said opening for~~  
11    ~~allowing said electrode pad and said circuit substrate to be electrically connectable to each~~  
12    ~~other;~~

13           ~~said method comprising:~~

14           ~~a first step in which one faces of a plurality of sealing walls are closely adhered to one~~  
15    ~~main surface of said first substrate which has a plurality of electronic circuit devices formed on~~  
16    ~~said one main surface in a plurality of circuit regions and a plurality of electrode pads in~~  
17    ~~electric connection with said plurality of electronic circuit devices, said plurality of sealing~~  
18    ~~walls each configured to enclose each of said plurality of electronic circuit devices with each of~~  
19    ~~said plurality of electrode pads arranged outside of each of said plurality of sealing walls, and~~  
20    ~~in which said second substrate is closely adhered to the other faces of said plurality of sealing~~

~~walls, said second substrate having a plurality of openings at sites confronting said plurality of electrode pads;~~

~~a second step in which an electrically conductive member is formed on each of said plurality of electrode pads, said electrically conductive member, being electrically connected with each of said plurality of electrode pads; and~~

~~a third step in which said first substrate, together with said second substrate, is severed for each of said plurality of circuit regions, to obtain a plurality of electronic components.~~

14 (Previously Amended). A method of manufacturing an electronic component to be mounted on a circuit board, said electronic component comprising:

a first substrate having an electronic circuit device and an electrode pad on one main surface of said first substrate in electrical connection with said electronic circuit device;

a sealing wall whose one face is closely adhered to said one main surface of said first substrate, said sealing wall being configured, to enclose said electronic circuit device with said electrode pad arranged outside of said sealing wall;

a second substrate closely adhered to the other face of said sealing wall;

an opening formed in said second substrate at a site confronting said electrode pad; and

an electrically conductive member extending through the interior of said opening for allowing said electrode pad and said circuit substrate to be electrically connectable to each other;

said method comprising:

14 a first step in which one faces of a plurality of sealing walls are closely adhered to one  
15 main surface of said first substrate which has a plurality of electronic circuit devices formed on  
16 said one main surface in a plurality of circuit regions and a plurality of electrode pads in  
17 electric connection with said plurality of electronic circuit devices, said plurality of sealing  
18 walls each configured to enclose each of said plurality of electronic circuit devices with each of  
19 said plurality of electrode pads arranged outside of each of said plurality of sealing walls, and  
20 in which said second substrate is closely adhered to the other faces of said plurality of sealing  
21 walls, said second substrate having a plurality of openings at sites confronting said plurality of  
22 electrode pads said plurality of sealing walls are closely adhered to said first substrate after  
23 formation of said plurality of sealing walls onto said second substrate,

24 a second step in which an electrically conductive member is formed on each of said  
25 plurality of electrode pads, said electrically conductive member, being electrically connected  
26 with each of said plurality of electrode pads; and

27 a third step in which said first substrate, together with said second substrate, is severed  
28 for each of said plurality of circuit regions, to obtain a plurality of electronic components.

1 15. (Currently Amended) A method of manufacturing an electronic component according to  
2 claim [13] 18, wherein said first step includes a step in which said plurality of sealing walls are  
3 closely adhered to said second substrate after formation of said plurality of sealing walls onto  
4 said first substrate.

1 16 (Currently Amended). A method of manufacturing an electronic component according to  
2 claim ~~[13]~~ 14, wherein  
3 said second step includes a step in which said electrically conductive member is formed on  
4 each of said plurality of electrode pads through a corresponding one of said plurality of  
5 openings.

1 17. (Currently Amended) A method of manufacturing an electronic component according to  
2 claim ~~[13]~~ 14, wherein  
3 said electrically conductive member comprises a bump.

1 18. (Previously Amended) A method of manufacturing an electronic component to be mounted  
2 on a circuit board, said electronic component comprising:

3 a first substrate having an electronic circuit device and an electrode pad on one main  
4 surface of said first substrate in electrical connection with said electronic circuit device;

5 a sealing wall whose one face is closely adhered to said one main surface of said first  
6 substrate, said sealing wall being configured, to enclose said electronic circuit device with said  
7 electrode pad arranged outside of said sealing wall;

8 a second substrate closely adhered to the other face of said sealing wall;

9 an opening formed in said second substrate at a site confronting said electrode pad; and

10 an electrically conductive member extending through the interior of said opening for  
11 allowing said electrode pad and said circuit substrate to be electrically connectable to each  
12 other, said electrically conductive member comprises: a first bump disposed on each of said

13 plurality of electrode pads for electrical connection with said each of said plurality of electrode  
14 pads; and a second bump disposed on top of said first bump for electrical and physical  
15 connection with said circuit board;

16 said method comprising:

17 a first step in which one faces of a plurality of sealing walls are closely adhered to one  
18 main surface of said first substrate which has a plurality of electronic circuit devices formed on  
19 said one main surface in a plurality of circuit regions and a plurality of electrode pads in  
20 electric connection with said plurality of electronic circuit devices, said plurality of sealing  
21 walls each configured to enclose each of said plurality of electronic circuit devices with each of  
22 said plurality of electrode pads arranged outside of each of said plurality of sealing walls, and  
23 in which said second substrate is closely adhered to the other faces of said plurality of sealing  
24 walls, said second substrate having a plurality of openings at sites confronting said plurality of  
25 electrode pads said plurality of sealing walls are closely adhered to said first substrate after  
26 formation of said plurality of sealing walls onto said second substrate,

27 a second step in which an electrically conductive member by forming said first bump on  
28 each of said plurality of electrode pads through a corresponding one of said plurality of  
29 openings, after which said second bump is formed on top of said first bump, said electrically  
30 conductive member, being electrically connected with each of said plurality of electrode pads;  
31 and;

32 third step in which said first substrate, together with said second substrate, is severed  
33 for each of said plurality of circuit regions, to obtain a plurality of electronic components.

1           19. (Currently Amended) A method of manufacturing an electronic component  
2 according to claim [~~13~~] 14, wherein

3           a first electrically conductive member is formed on an inner wall of each of said  
4 plurality of openings, said first electrically conductive member being electrically  
5 connectable to said circuit board, and wherein

6           said second step includes a step in which, a second electrically conductive  
7 member is formed on each of said plurality of electrode pads, said second electrically  
8 conductive member electrically connecting said first electrically conductive member and  
9 each of said plurality of electrode pads.

1           20. (Currently Amended) A method of manufacturing an electronic component  
2 according to claim [~~13~~] 14, wherein  
3 said second step is carried out after said first step.